

Sensors and Materials

Special Issue on Recent Advances in Soft Computing and Sensors for Industrial Applications

Call for Papers

Artificial intelligence (AI) gives computers the ability to see what is happening in the world around them. In recent years, developments have led to the widespread use of soft computing (SC) in industry. SC is a field of computer science that resembles the processes of the human brain and takes an integrated view of computing to solve real-life problems. It is a collection of methodologies that investigate, simulate, and analyze very complex issues and phenomena. On the other hand, during the past few years, a great number of systems, algorithms, mechanisms, and methodologies have been proposed for sensor information fusion. However, researchers of sensor networks and information fusion are still searching for more SC- and learning-based fusion techniques, system architectures, data analysis, message control algorithms, and so on. The goal of this SI is to highlight state-of-the-art works that deal with the use of SC for industrial applications. Papers on both theoretical studies and practical applications are welcomed. Submitted papers should present original, unpublished work relevant to one of the topics of the SI. All submitted papers will be evaluated on the basis of relevance, the significance of the contribution, technical quality, scholarship, and the quality of presentation by at least three independent reviewers.

Scope: (including but not limited to)

1. SC using sensors for industrial applications
2. SC using sensors for consumer electronics.
3. SC using sensors for industrial electronics.
4. SC using sensors for social networks
5. Distributed machine learning, optimization, and applications.

Important Dates:

Submission deadline: July 7, 2021
First round decision: September 9, 2021
First round revision submission: October 6, 2021
Second round decision: December 8, 2021
Second round revision submission: January 6, 2022
Final decision: February 1, 2022
Tentative publication: April 2022

Guest Editor: Prof. Chih-Hsien Hsia

(Dept. Computer Science and Information Engineering, National Ilan University, Taiwan)

Journal website: <https://myukk.org/>

Submit to: Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>)

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors should bear the proofreading fee (JPY 10000–30000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of *Sensors and Materials*

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3827-8549, Fax: +81-3-3827-8547

E-mail: myukk@myu-inc.jp

